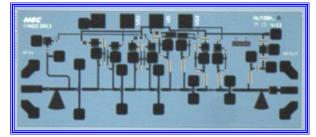


NORTHROP GRUMMAN

Product Datasheet

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X = 2.0mm Y = 0.85mm Product Features

- RF frequency: 80-100 GHz
- Broadband Operation
- Linear gain: 29 dB, typical
- Noise Figure: 2 dB, typical
- P1dB : 3 dBm *
- Microstrip Topology MMIC, In-line Input & Output
- 0.1 um InP HEMT Process
- 3 mil substrate
- DC Power: < 35 mW</p>
- Die Size 1.7 sq. mm

Performance Characteristics (Ta = 25° C)

Specification	Min	Тур	Max	Unit
Frequency	80		100	GHz
Linear Gain	25	29		dB
Input Return Loss	4	10		dB
Output Return Loss	5	12		dB
Noise Figure		2	3.5	dB
Noise Figure (Ave.)		2.6	3	dB
P1dB *		3		dBm
Vd		1.3		V
Vg1=Vg2		-0.1		V
ld1		25.5		mA

Applications

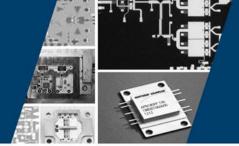
- W-Band Imaging
- Sensors
- Radar
- Short Haul / High Capacity Links
- W-Band Communication Links

Product Description

The ALP280 W-band InP HEMT Low Noise Amplifier is a 5-Stage, broadband, ultra low noise amplifier MMIC. It can be used in applications such as W-band Imaging, Radar, commercial digital microwave radios and wireless LANs. The small die size allows for extremely compact packaging. To ensure rugged and reliable operation, HEMT devices are fully passivated. Both bond pad and backside metallization are Ti/Au, which is compatible with conventional die attach, thermocompression and thermosonic wire bonding assembly techniques.

Absolute Maximum Ratings (Ta = 25° C)

Parameter	Min	Max	Unit		
Vd1		1.3	V		
Vg1, vg2	-1	0.4	V		
ld2		25.5	mA		
Input Drive Level *		-24	dBm		
Assy. Temperature		150	deg. C		
* Estimated					

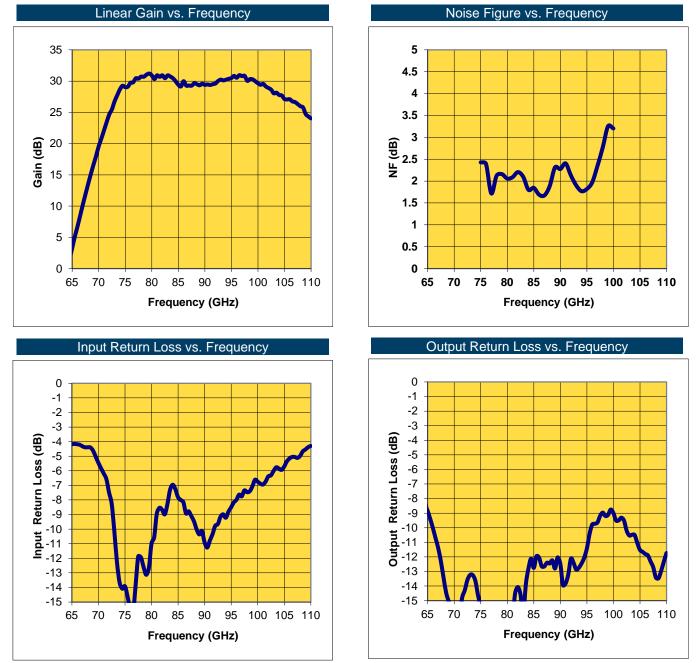




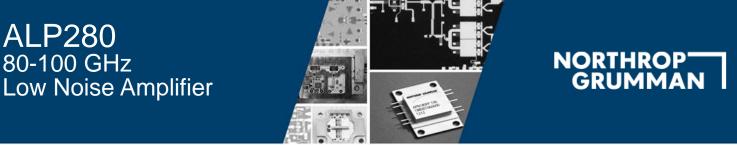
Product Datasheet

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Measured Performance Characteristics (Typical Performance at 25° C) Vd = 1.3 V, Id = 25.5 mA* - Wideband Performance



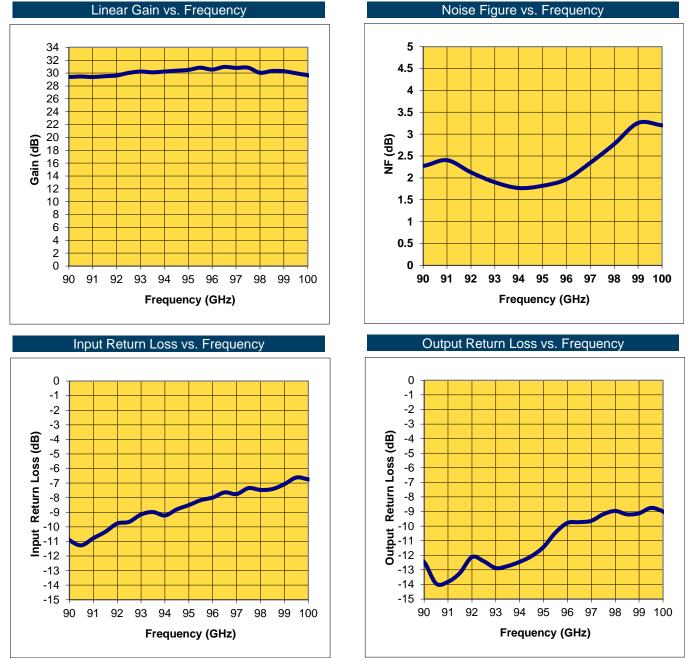
^{*} On-Wafer, Vg1=Vg2



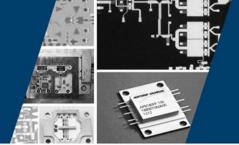
Product Datasheet

Revision: April 2014

Measured Performance Characteristics (Typical Performance at 25° C) Vd = 1.3 V, Id = 25.5 mA* - Performance from 90 GHz to 100 GHz



* On-Wafer, Vg1=Vg2

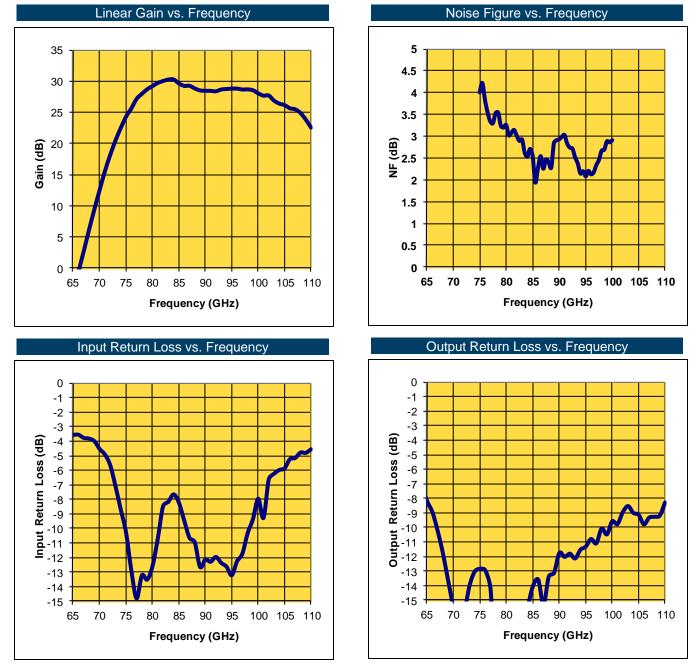




Product Datasheet

Revision: April 2014

Measured Performance Characteristics (Typical Performance at 25° C) Vd = 1.3 V, Id = 25.5 mA** - Wideband Performance



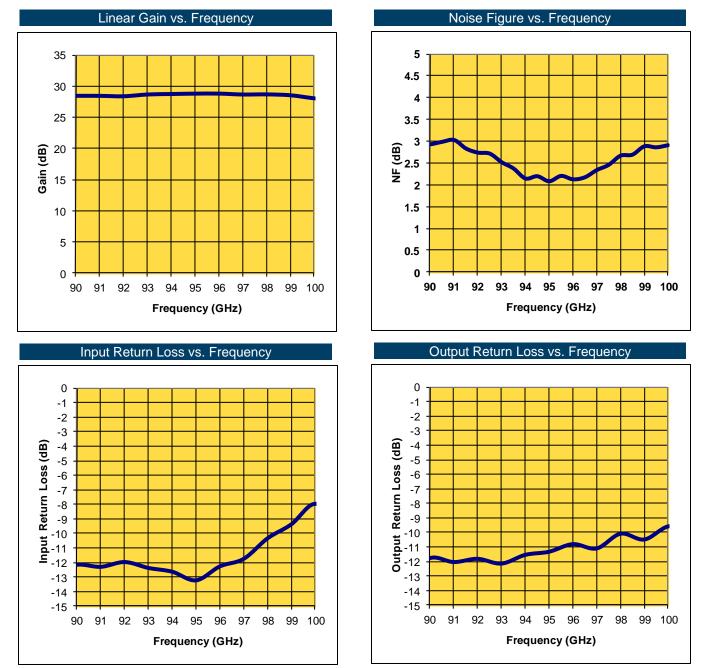
* On-Wafer, Vg1 & Vg2 biased Independently



Product Datasheet

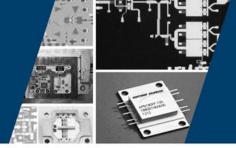
Revision: April 2014

Measured Performance Characteristics (Typical Performance at 25° C) Vd = 1.3 V, Id = 25.5 mA** - Performance from 90 GHz to 100 GHz



* On-Wafer, Vg1 & Vg2 biased Independently



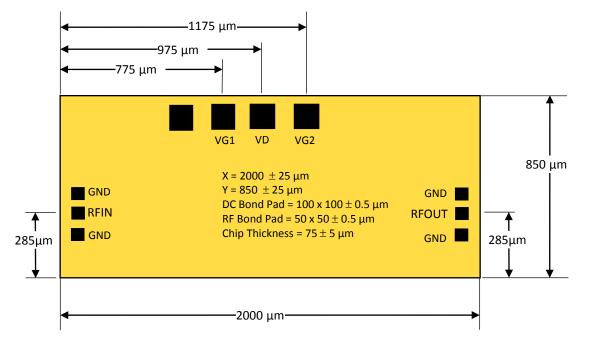




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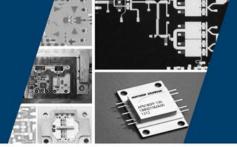
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Die Size and Bond Pad Locations (Not to Scale)



Recommended Assembly Notes

- 1. Bypass caps should be 100 pF (approximately) ceramic (single-layer) placed no farther than 30 mils from the amplifier.
- 2. Best performance obtained from use of < 6 mil (long) by 1.5 by 0.5 mil ribbons on input and output.

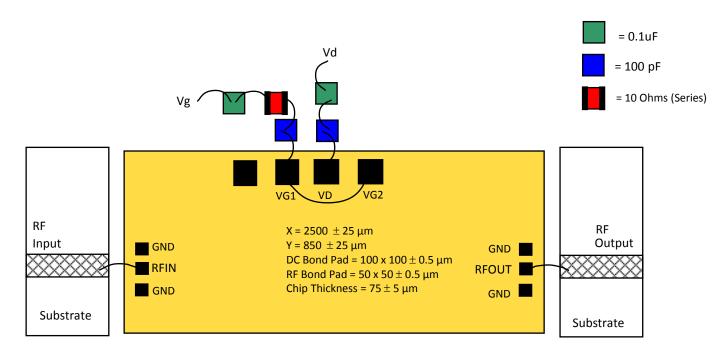


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Suggested Bonding Arrangement



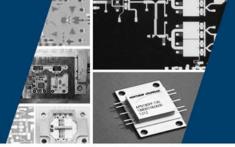
Biasing/De-Biasing Details:

Bias up sequence:

Pinch-off the device by setting Vg1 = Vg2= -0.6 and Vd = 0V Increase Vd to the desired value Adjust Vg1=Vg2 to realize the desired Id (Nominal Current for Id for Vg1 = Vg2 biased on is 25.5 mA)

Bias down sequence:

Reduce Vg1=Vg2 down to -0.6V Lower Vd to 0V Lower Vg1=Vg2 to 0V

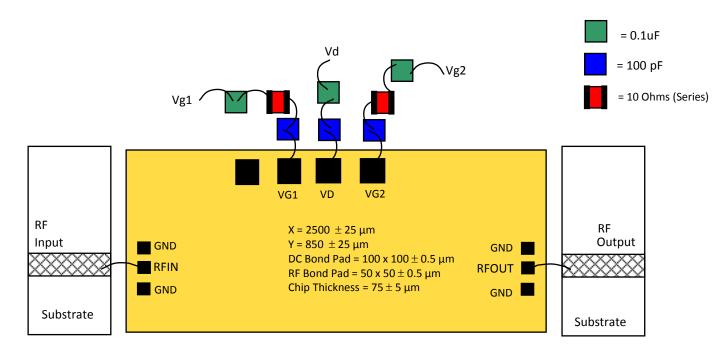


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Suggested Bonding Arrangement (Alternate Bias)



Biasing/De-Biasing Details:

Bias up sequence:

Pinch-off the device by setting Vg1 = Vg2= -0.6 and Vd = 0V Increase Vd to the desired value Adjust Vg1 to realize the desired Id (Nominal Current for Id for Vg1 biased on is 13.5 mA) Adjust Vg2 to realize the desired Id (Nominal Current for Id for both Vg1 and Vg2 biased on is 25.5 mA)

Bias down sequence:

Reduce Vg2 down to -0.6V Reduce Vg1 down to -0.6V Lower Vd to 0V Lower Vg1 and Vg2 to 0V

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